BGA Heat Sink - High Performance maxiFLOW w/Thermal Tape





ATS Part#: ATS-52170P-C1-R0

Description: 17.00 x 17.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW w/Thermal

Tape

Heat Sink Type: maxiFLOW
Heat Sink Attachment: Thermal Tape

Equivalent Part Number: ATS-52170P-C2-R0

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low
- · Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	8.3 °C/W	6.9 °C/W	6 °C/W	5.4 °C/W	5 °C/W	4.6 °C/W	4.4 °C/W
	Ducted Flow	6.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image Dimension A		Dimension B	Dimension C	Dimension D	TIM	Finish
	17.00 mm	17.00 mm	17.50 mm	31.94 mm	T412	BLUE-ANODIZED
*Image above is for illustration purpose only.	 Dimension ATS-5217 (Saint-Go) Thermal papplication ATS reserperforman ATS certification 	OP-C2-R0 is the example of the control of the contr	emponent size. The provided for reference or change its provided k assembly is RoHS assembly is RoHS	oly with an equivalent nce only. Actual performation ducts without notice	t thermal formance	interface material may vary by



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